REPLACEMENT SHEET

APPLN. FILING DATE: OCTOBER 13, 2000
TITLE: METHOD FOR MANUFACTURING ELECTRONIC PARTS
INVENTOR(S): AKIO KATSUBE ET AL.
APPLN. NO.: 09/689,774

SHEET 1 OF 6

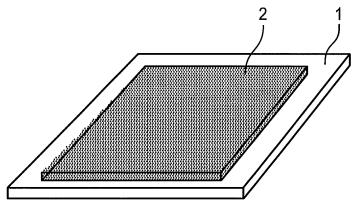
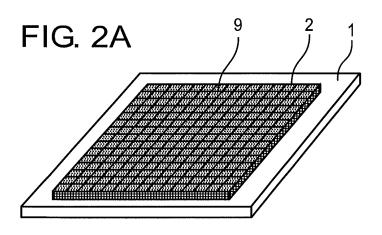


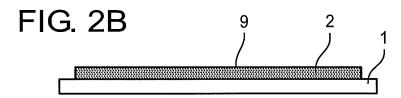
FIG. 1A

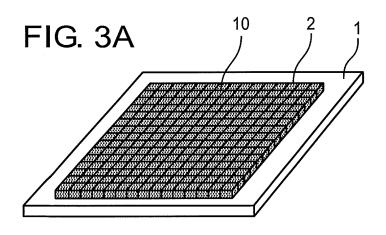


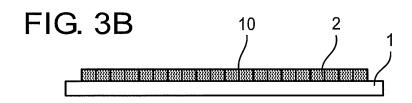
FIG. 1B

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SHEET 2 OF 6









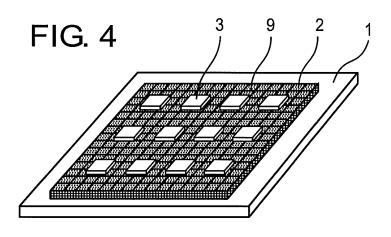
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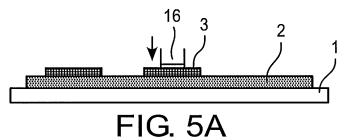
TITLE: METHOD FOR MANUFACTURING ELECTRONIC PARTS

INVENTOR(S): AKIO KATSUBE ET AL. APPLN. NO.: 09/689,774

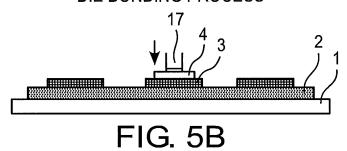
SHEET 3 OF 6



SUBSTRATE MOUNTING PROCESS



DIE BONDING PROCESS



WIRE BONDING PROCESS

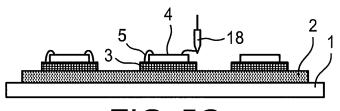


FIG. 5C

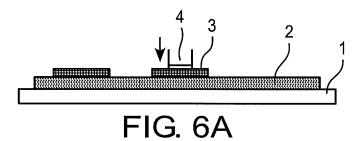
REPLACEMENT SHEET

APPLN. FILING DATE: OCTOBER 13, 2000

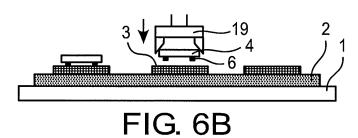
TITLE: METHOD FOR MANUFACTURING ELECTRONIC

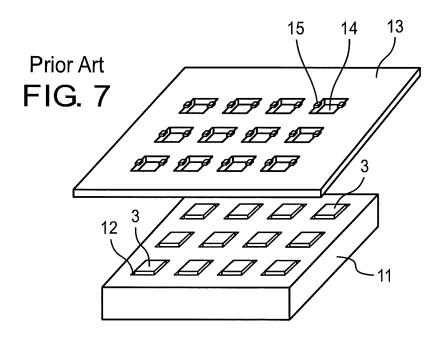
PARTS
INVENTOR(S): AKIO KATSUBE ET AL.
APPLN. NO.: 09/689,774 SHEET 4 OF 6

SUBSTRATE MOUNTING PROCESS



BUMP BONDING PROCESS



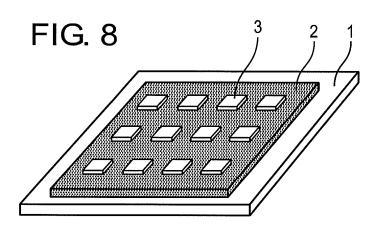


REPLACEMENT SHEET
APPLN. FILING DATE: OCTOBER 13, 2000
TITLE: METHOD FOR MANUFACTURING ELECTRONIC

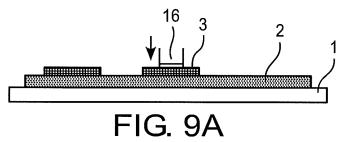
PARTS

INVENTOR(S): AKIO KATSUBE ET AL. APPLN. NO.: 09/689,774

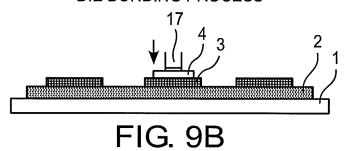
SHEET 5 OF 6



SUBSTRATE MOUNTING PROCESS



DIE BONDING PROCESS



WIRE BONDING PROCESS

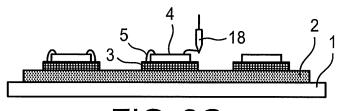


FIG. 9C

REPLACEMENT SHEET

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TITLE: METHOD FOR MANUFACTURING ELECTRONIC PARTS
INVENTOR(S): AKIO KATSUBE ET AL.

APPLN. No.: 09/689,774

SHEET 6 OF 6

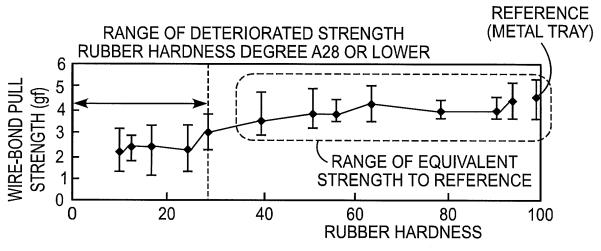
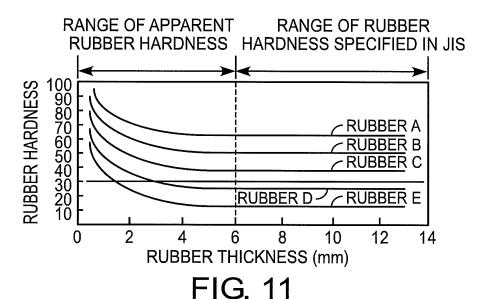
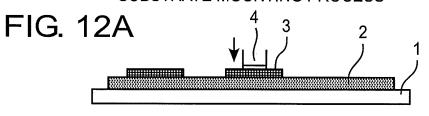


FIG. 10



SUBSTRATE MOUNTING PROCESS



BUMP BONDING PROCESS

